



## **SEMI 3D & Systems Summit to Spotlight Latest Trends in Heterogeneous Integration, Hybrid Bonding, Chiplet Design And Photonics – April 4, 2023**

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DRESDEN, Germany, April 4, 2023 — Leading experts in 3D integration and systems for semiconductor manufacturing will gather at the annual SEMI [3D & Systems Summit](#), June 26-28, 2023 in Dresden, for insights into the latest heterogeneous integration innovations for semiconductor applications enabling the future of intelligent systems. The most prominent names in 3D integration microelectronics manufacturing will showcase their latest products and technologies. [Registration](#) is open.



“We look forward to hosting industry leaders at the 3D & Systems Summit as they deliver insights into cutting-edge advanced packaging solutions,” said Laith Altimime, President of SEMI Europe. “Packaging innovations are critical to semiconductor industry growth, increasing chip performance, reducing power consumption and enabling smaller end devices for emerging and growing segments including autonomous driving, 6G, Internet of Things (IoT), artificial intelligence (AI), and machine learning.”

Themed *Smarter Systems through Heterogeneous Integration*, this year’s 3D & Systems Summit will feature a broader scope of topics including:

- Advanced Packaging: Enabling Moore’s Law’s – The Next Frontier
- Market Briefing and Technical Roadmap
- Industrialization and Mass Adoption of 3D Technologies
- Hybrid Bonding Developments
- Chiplet Design Packaging: Architectures and Challenges
- Novel Processes and Interconnect Solutions for 3D
- Photonics Integration
- Sustainability
- Applications Enabled by 3D

### **3D & Systems Summit Distinguished Speakers**

- **Seung Kang**, VP of Strategy, [Adeia, Inc.](#)
- **Raja Swaminathan**, Corporate VP, [AMD](#)
- **Rozalia Beica**, VP Strategic Marketing & Business Development, Microelectronics Business Unit, [AT&S China](#)
- **Yoan Dupret**, Managing Director and CTO, [Menta](#)
- **Pascal Metzger**, CEO, [SET Corporation S.A.](#)
- **Luc Augustin**, CTO, [Smart Photonics](#)
- **E. Jan Vardaman**, President, [TechSearch International, Inc.](#)
- **Emilie Jolivet**, Semiconductor, Memory and Computing Division Director, [Yole Group](#)

### **Global Leaders to Present**

3D & Systems Summit presenters also include experts from these global leaders:

- Adeia
- AMD

- ASML
- AT&S China
- Besi
- CEA-Leti
- EPIC
- EV Group
- Fraunhofer IIS-EAS
- Fraunhofer IZM-ASSID
- imec
- Intel Corporation
- KLA Corporation
- Menta
- MKS-Atotech
- Research Fab Microelectronics Germany (FMD) and Fraunhofer Group for Microelectronics
- SET Corporation S.A.
- Siemens EDA
- Smart Photonics
- SPTS Technologies Ltd., a KLA company
- SÜSS MicroTec
- TechSearch International
- Yole Group

#### **Exhibition and Premium Networking Opportunities**

The 3D & Systems Summit will feature business-to-business matchmaking and networking for exploring new partnerships and other business opportunities. This year's networking dinner will take place on the Elbe River cruise.

To reserve an exhibition space, contact [euevents@semi.org](mailto:euevents@semi.org).

For more details, please visit the [3D & Systems Summit](#) website.

#### **About SEMI**

SEMI connects more than 2,500 member companies and 1.3 million professionals worldwide to advance electronics design and manufacturing technology and business. SEMI members are responsible for the innovations in materials, design, equipment, software, devices, and services that enable more innovative, faster, powerful, and affordable electronic products. Electronic System Design Alliance (ESD Alliance), FlexTech, the Fab Owners Alliance (FOA), the MEMS & Sensors Industry Group (MSIG), and SOI Consortium are SEMI Strategic Technology Communities.

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*Source: SEMI*

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